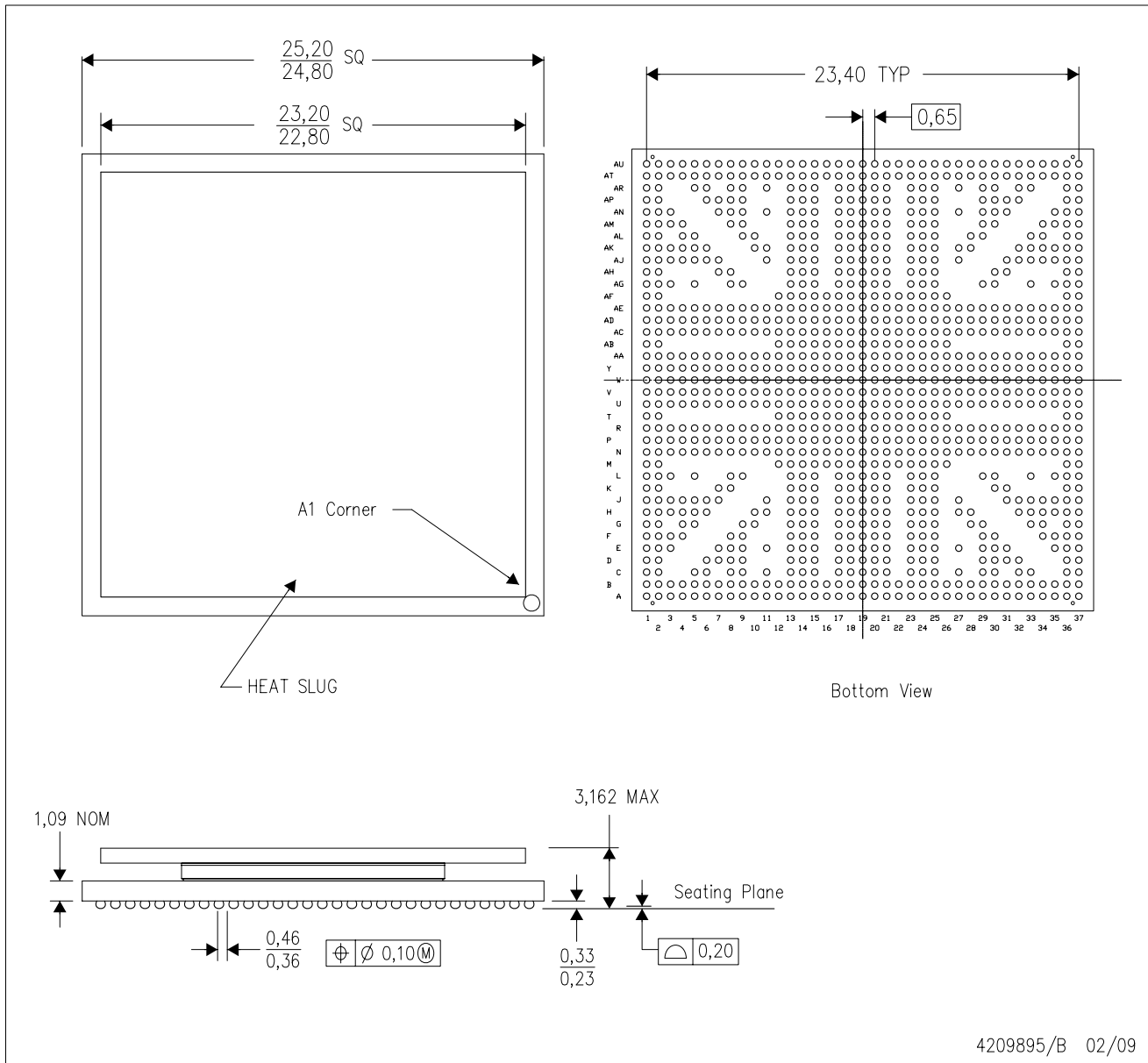


ZMW (S-PBGA-N1061)

PLASTIC BALL GRID ARRAY



- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - Thermally enhanced molded plastic package with heat slug (HSL).
 - Flip chip application only.
 - This is a Pb-free solder ball design.

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